File   View   Edit   Tools   Window   Help

- BRS: knall
- BRS: 19 21 23
- BRS: 32 with 33
- Pending
- Active
  - L1: (22) (((((carrier near9 cavity) with ((open $5 via hole aperture perforat $4) 0
  - L2: (458238) (@ad @pd) > "20040425"
  - L3: (138) lip near4 (portion section) near4 bottom adj surface
  - L4: (30841) frustoconical
  - L5: (14) 3 and 4
  - L6: (4) 3 same 4
- Failed
- Saved
  - (1) 09/848877
  - (1738) "KONINKLIJKE PHILIPS".as.
  - (3) 09/344279
  - (8924363) (open $5 via hole aperture perforat $4)
  - (408215) (mcm (multi adj chip adj module)) (stack $4 near2 (package chip module)) (
  - (682754) cavity
  - (6829277) (open $5 via hole aperture perforat $4)
  - (408517) (mcm (multi adj chip adj module)) (stack $4 near2 (package chip module)) (
  - (683188) cavity
  - (30232) frustoconical
  - (30534) frustocon $5
  - (63691) frustocon $5 frusto adj conic $2
  - (1134474) carrier

DBs   USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB   Plurals

Default operator   OR   Highlight all hit terms initially

Browse   Queue   Clear

3 same 4

Aug 2004

U	-1	Inventor	Document	Issue	P	Title	Current	Current XR	Retrieval	S	C	P		3			Image Doc.	P
1		Moden, Walt	US 2001004	20011	1	Stackable ceramic fbga for high thermal appl	257/686	257/E23.00		✓				✓			US 200100	
2		Moden, Walt	US 6650007	20031	1	Stackable ceramic fbga for high thermal appl	257/686	257/685;		✓				✓			US 665000	
3		Moden, Walt	US 6297548	20011	1	Stackable ceramic FBGA for high thermal ap	257/686	257/687;		✓			✓				US 629754	
4		Moden, Walt	US 2004010	20040	1	Stackable ceramic FBGA for high thermal ap	257/200			✓							US 200401	

Ready   NUM